

L Number	Hits	Search Text	DB	Time stamp
1	3106	324/754.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 14:53
2	747	324/758.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 14:53
3	3027	324/765.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 14:53
4	6438	324/754.ccls. or 324/758.ccls. or 324/765.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 14:55
5	669	(automated and camera and (contact adj3 surface) and alignment)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 15:04
6	15	(324/754.ccls. or 324/758.ccls. or 324/765.ccls.) and ((automated and camera and (contact adj3 surface) and alignment))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 14:57
7	3048	(camera and (contact adj3 surface) and alignment)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 15:05
8	56	(324/754.ccls. or 324/758.ccls. or 324/765.ccls.) and ((camera and (contact adj3 surface) and alignment))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 15:23
9	286	324/758.cor.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 15:40
10	219	324/754.ccls. and 324/758.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/12 15:40
-	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/03 10:18
-	53138	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/03 10:19
-	9052	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:21

	1115	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:22
	267	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:24
	204	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))) and (substrate with (removal or removed or removing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:26